

# RF Power Field Effect Transistors

## N-Channel Enhancement-Mode Lateral MOSFETs

Designed for broadband commercial and industrial applications with frequencies up to 1000 MHz. The high gain and broadband performance of these devices make them ideal for large-signal, common-source amplifier applications in 28 volt base station equipment.

### N-CDMA Application

- Typical Single-Carrier N-CDMA Performance:  $V_{DD} = 28$  Volts,  $I_{DQ} = 950$  mA,  $P_{out} = 27$  Watt Avg., Full Frequency Band (865-960 MHz), IS-95 CDMA (Pilot, Sync, Paging, Traffic Codes 8 Through 13) Channel Bandwidth = 1.2288 MHz. PAR = 9.8 dB @ 0.01% Probability on CCDF.  
Power Gain — 20.2 dB  
Drain Efficiency — 31%  
ACPR @ 750 kHz Offset = -47.1 dBc in 30 kHz Bandwidth

### GSM EDGE Application

- Typical GSM EDGE Performance:  $V_{DD} = 28$  Volts,  $I_{DQ} = 700$  mA,  $P_{out} = 60$  Watts Avg., Full Frequency Band (865-960 MHz or 921-960 MHz)  
Power Gain — 20 dB  
Drain Efficiency — 40%  
Spectral Regrowth @ 400 kHz Offset = -63 dBc  
Spectral Regrowth @ 600 kHz Offset = -78 dBc  
EVM — 1.8% rms

### GSM Application

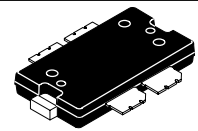
- Typical GSM Performance:  $V_{DD} = 28$  Volts,  $I_{DQ} = 700$  mA,  $P_{out} = 125$  Watts, Full Frequency Band (921-960 MHz)  
Power Gain — 19 dB  
Drain Efficiency — 62%
- Capable of Handling 10:1 VSWR, @ 28 Vdc, 880 MHz, 125 Watts CW Output Power

### Features

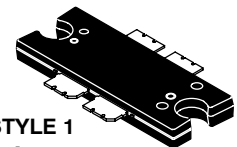
- Characterized with Series Equivalent Large-Signal Impedance Parameters
- Internally Matched for Ease of Use
- Qualified Up to a Maximum of 32  $V_{DD}$  Operation
- Integrated ESD Protection
- 200°C Capable Plastic Package
- N Suffix Indicates Lead-Free Terminations. RoHS Compliant.
- In Tape and Reel. R1 Suffix = 500 Units per 44 mm, 13 inch Reel.

**MRF6S9125NR1**  
**MRF6S9125NBR1**

**865-960 MHz, 27 W AVG., 28 V**  
**SINGLE N-CDMA, GSM EDGE**  
**LATERAL N-CHANNEL**  
**RF POWER MOSFETs**



**CASE 1486-03, STYLE 1**  
**TO-270 WB-4**  
**PLASTIC**  
**MRF6S9125NR1**



**CASE 1484-04, STYLE 1**  
**TO-272 WB-4**  
**PLASTIC**  
**MRF6S9125NBR1**

**Table 1. Maximum Ratings**

Rating	Symbol	Value	Unit
Drain-Source Voltage	$V_{DSS}$	-0.5, +68	Vdc
Gate-Source Voltage	$V_{GS}$	-0.5, +12	Vdc
Total Device Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25°C	$P_D$	398 2.3	W W/°C
Storage Temperature Range	$T_{stg}$	-65 to +150	°C
Operating Junction Temperature	$T_J$	200	°C

**Table 2. Thermal Characteristics**

Characteristic	Symbol	Value (1,2)	Unit
Thermal Resistance, Junction to Case Case Temperature 80°C, 125 W CW Case Temperature 76°C, 27 W CW	$R_{\theta JC}$	0.44 0.45	°C/W

**Table 3. ESD Protection Characteristics**

Test Methodology	Class
Human Body Model (per JESD22-A114)	1B (Minimum)
Machine Model (per EIA/JESD22-A115)	C (Minimum)
Charge Device Model (per JESD22-C101)	IV (Minimum)

**Table 4. Moisture Sensitivity Level**

Test Methodology	Rating	Package Peak Temperature	Unit
Per JESD 22-A113, IPC/JEDEC J-STD-020	3	260	°C

**Table 5. Electrical Characteristics** ( $T_C = 25^\circ\text{C}$  unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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**Off Characteristics**

Zero Gate Voltage Drain Leakage Current ( $V_{DS} = 68 \text{ Vdc}$ , $V_{GS} = 0 \text{ Vdc}$ )	$I_{DSS}$	—	—	10	$\mu\text{Adc}$
Zero Gate Voltage Drain Leakage Current ( $V_{DS} = 28 \text{ Vdc}$ , $V_{GS} = 0 \text{ Vdc}$ )	$I_{DSS}$	—	—	1	$\mu\text{Adc}$
Gate-Source Leakage Current ( $V_{GS} = 5 \text{ Vdc}$ , $V_{DS} = 0 \text{ Vdc}$ )	$I_{GSS}$	—	—	1	$\mu\text{Adc}$

**On Characteristics**

Gate Threshold Voltage ( $V_{DS} = 10 \text{ Vdc}$ , $I_D = 400 \mu\text{Adc}$ )	$V_{GS(th)}$	1	2.1	3	Vdc
Gate Quiescent Voltage ( $V_{DS} = 28 \text{ Vdc}$ , $I_D = 950 \text{ mAdc}$ )	$V_{GS(Q)}$	2	2.89	4	Vdc
Drain-Source On-Voltage ( $V_{GS} = 10 \text{ Vdc}$ , $I_D = 2.74 \text{ Adc}$ )	$V_{DS(on)}$	0.05	0.23	0.3	Vdc
Forward Transconductance ( $V_{DS} = 10 \text{ Vdc}$ , $I_D = 8 \text{ Adc}$ )	$g_{fs}$	—	6	—	S

**Dynamic Characteristics** <sup>(3)</sup>

Reverse Transfer Capacitance ( $V_{DS} = 28 \text{ Vdc} \pm 30 \text{ mV(rms)ac}$ @ 1 MHz, $V_{GS} = 0 \text{ Vdc}$ )	$C_{rss}$	—	2	—	pF
Output Capacitance ( $V_{DS} = 28 \text{ Vdc} \pm 30 \text{ mV(rms)ac}$ @ 1 MHz, $V_{GS} = 0 \text{ Vdc}$ )	$C_{oss}$	—	60	—	pF

**Functional Tests** (In Freescale Test Fixture, 50 ohm system)  $V_{DD} = 28 \text{ Vdc}$ ,  $I_{DQ} = 950 \text{ mA}$ ,  $P_{out} = 27 \text{ W Avg}$ . N-CDMA,  $f = 880 \text{ MHz}$ , Single-Carrier N-CDMA, 1.2288 MHz Channel Bandwidth Carrier. ACPR measured in 30 kHz Channel Bandwidth @  $\pm 750 \text{ kHz}$  Offset. PAR = 9.8 dB @ 0.01% Probability on CCDF.

Power Gain	$G_{ps}$	19	20.2	24	dB
Drain Efficiency	$\eta_D$	29	31	—	%
Adjacent Channel Power Ratio	ACPR	—	-47.1	-45	dBc
Input Return Loss	IRL	—	-16	-9	dB

1. MTTF calculator available at <http://www.freescale.com/rf>. Select Tools/Software/Application Software/Calculators to access the MTTF calculators by product.
2. Refer to AN1955, *Thermal Measurement Methodology of RF Power Amplifiers*. Go to <http://www.freescale.com/rf>. Select Documentation/Application Notes - AN1955.
3. Part is internally input matched.

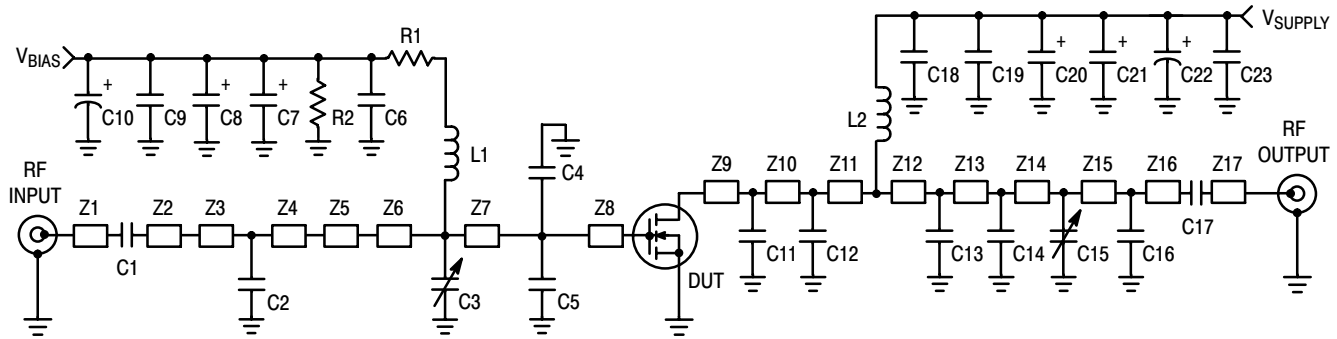
(continued)

**Table 5. Electrical Characteristics** ( $T_C = 25^\circ\text{C}$  unless otherwise noted) (continued)

Characteristic	Symbol	Min	Typ	Max	Unit
<b>Typical GSM EDGE Performances</b> (In Freescale GSM EDGE Test Fixture, 50 ohm system) $V_{DD} = 28\text{ Vdc}$ , $I_{DQ} = 700\text{ mA}$ , $P_{out} = 60\text{ W Avg.}$ , 921-960 MHz, EDGE Modulation					
Power Gain	$G_{ps}$	—	20	—	dB
Drain Efficiency	$\eta_D$	—	40	—	%
Error Vector Magnitude	EVM	—	1.8	—	% rms
Spectral Regrowth at 400 kHz Offset	SR1	—	-63	—	dBc
Spectral Regrowth at 600 kHz Offset	SR2	—	-78	—	dBc

**Typical CW Performances** (In Freescale GSM Test Fixture, 50 ohm system)  $V_{DD} = 28\text{ Vdc}$ ,  $I_{DQ} = 700\text{ mA}$ ,  $P_{out} = 125\text{ W}$ , 921-960 MHz

Power Gain	$G_{ps}$	—	19	—	dB
Drain Efficiency	$\eta_D$	—	62	—	%
Input Return Loss	IRL	—	-12	—	dB
$P_{out}$ @ 1 dB Compression Point, CW ( $f = 880\text{ MHz}$ )	P1dB	—	125	—	W



Z1, Z17	0.200" x 0.080" Microstrip	Z10	0.057" x 0.620" Microstrip
Z2	1.060" x 0.080" Microstrip	Z11	0.119" x 0.620" Microstrip
Z3	0.382" x 0.220" Microstrip	Z12	0.450" x 0.220" Microstrip
Z4	0.108" x 0.220" Microstrip	Z13	0.061" x 0.220" Microstrip
Z5	0.200" x 0.420" x 0.620" Taper	Z14	0.078" x 0.220" Microstrip
Z6	0.028" x 0.620" Microstrip	Z15	0.692" x 0.080" Microstrip
Z7	0.236" x 0.620" Microstrip	Z16	0.368" x 0.080" Microstrip
Z8	0.050" x 0.620" Microstrip	PCB	Arlon GX-0300-55-22, 0.030", $\epsilon_r = 2.55$
Z9	0.238" x 0.620" Microstrip		

**Figure 1. MRF6S9125NR1(NBR1) Test Circuit Schematic**

**Table 6. MRF6S9125NR1(NBR1) Test Circuit Component Designations and Values**

Part	Description	Part Number	Manufacturer
C1	20 pF Chip Capacitor	600B200FT250XT	ATC
C2	6.2 pF Chip Capacitor	600B6R2BT250XT	ATC
C3, C15	0.8-8.0 pF Variable Capacitors, Gigatrim	27291SL	Johanson
C4, C5	11 pF Chip Capacitors	600B110FT250XT	ATC
C6, C18, C19	0.56 $\mu$ F, 50 V Chip Capacitors	C1825C564J5RAC	Kemet
C7, C8	47 $\mu$ F, 16 V Tantalum Capacitors	593D476X9016D2T	Vishay
C9, C23	47 pF Chip Capacitors	700B470FW500XT	ATC
C10	100 $\mu$ F, 50 V Electrolytic Capacitor	515D107M050BB6A	Vishay
C11, C12	12 pF Chip Capacitors	600B120FT250XT	ATC
C13, C14	5.1 pF Chip Capacitors	600B5R1BT250XT	ATC
C16	0.3 pF Chip Capacitor	700B0R3BW500XT	ATC
C17	39 pF Chip Capacitor	700B390FW500XT	ATC
C20, C21	22 $\mu$ F, 35 V Tantalum Capacitors	T491X226K035AS	Kemet
C22	470 $\mu$ F, 63 V Electrolytic Capacitor	SME63V471M12X25LL	United Chemi-Con
L1	7.15 nH Inductor	1606-7J	CoilCraft
L2	8.0 nH Inductor	A03T	CoilCraft
R1	15 $\Omega$ , 1/4 W Chip Resistor (1210)		
R2	560 k $\Omega$ , 1/8 W Resistor (1206)		

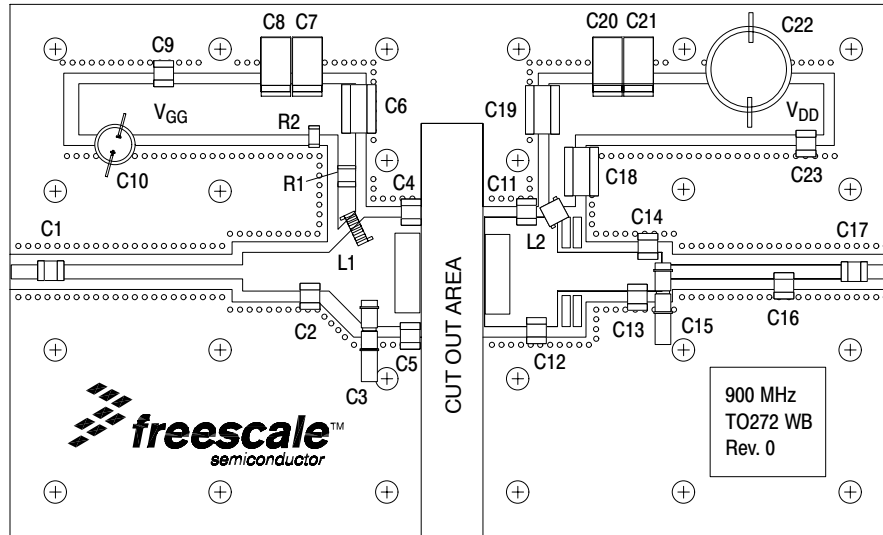


Figure 2. MRF6S9125NR1(NBR1) Test Circuit Component Layout

## TYPICAL CHARACTERISTICS

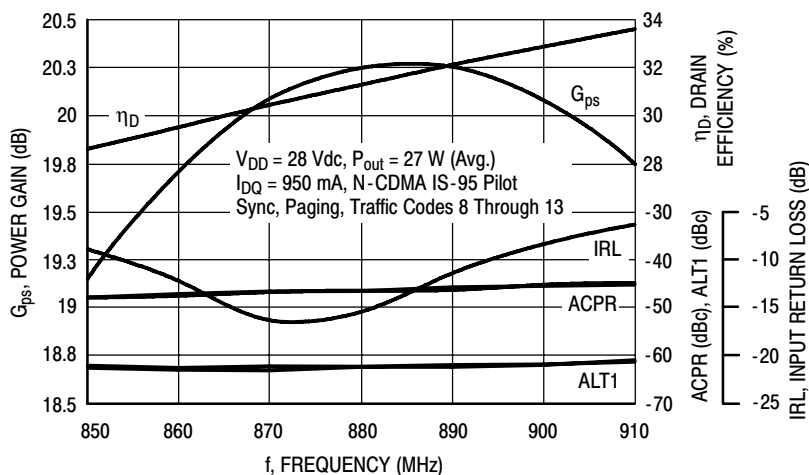


Figure 3. Single-Carrier N-CDMA Broadband Performance @  $P_{out} = 27$  Watts Avg.

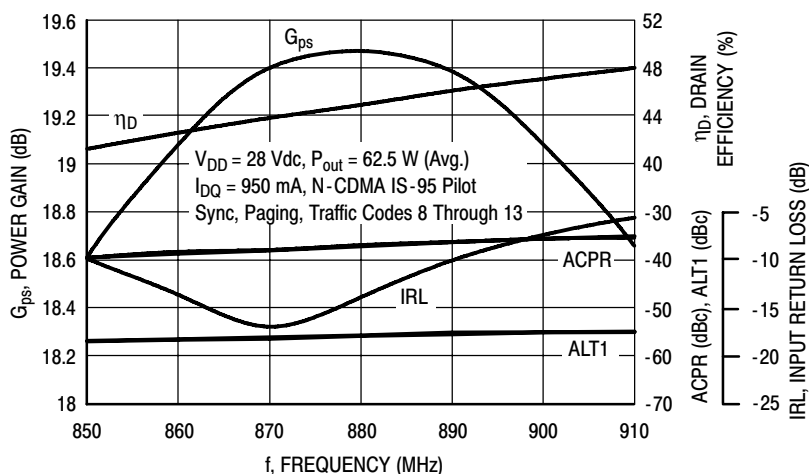


Figure 4. Single-Carrier N-CDMA Broadband Performance @  $P_{out} = 62.5$  Watts Avg.

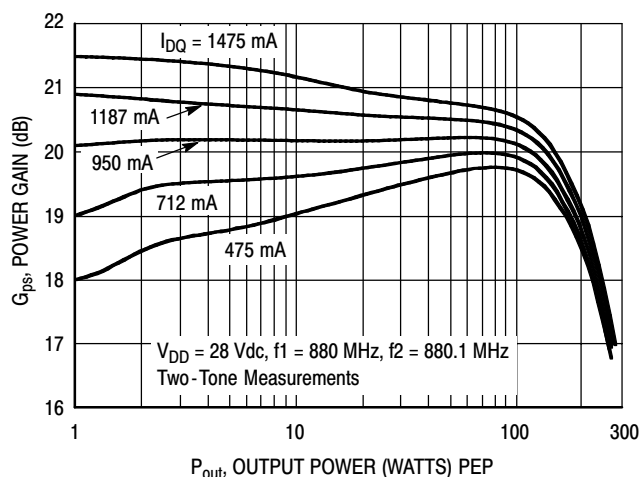


Figure 5. Two-Tone Power Gain versus Output Power

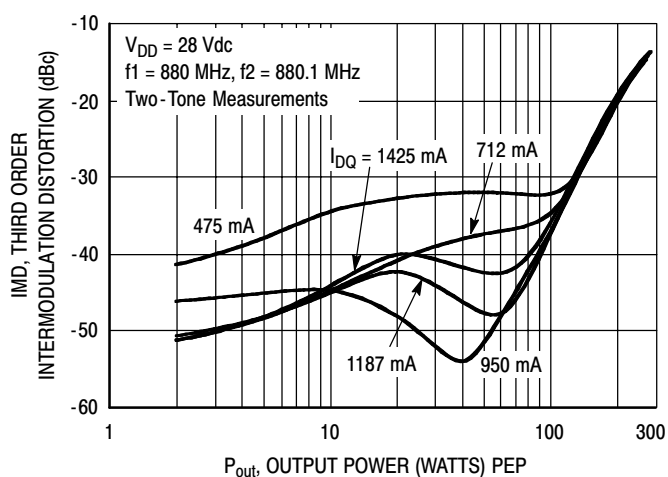


Figure 6. Third Order Intermodulation Distortion versus Output Power

## TYPICAL CHARACTERISTICS

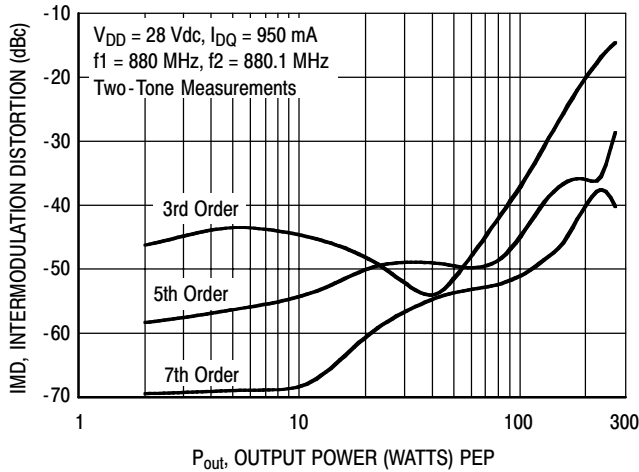


Figure 7. Intermodulation Distortion Products versus Output Power

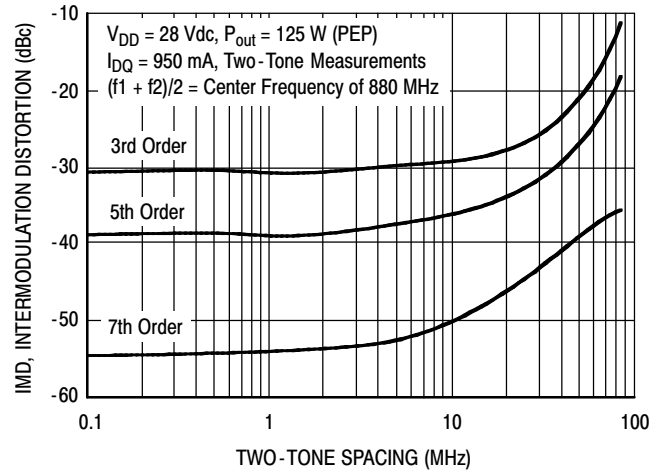


Figure 8. Intermodulation Distortion Products versus Tone Spacing

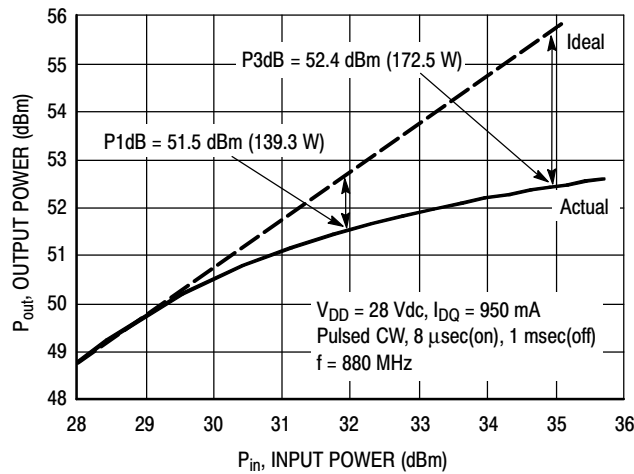


Figure 9. Pulse CW Output Power versus Input Power

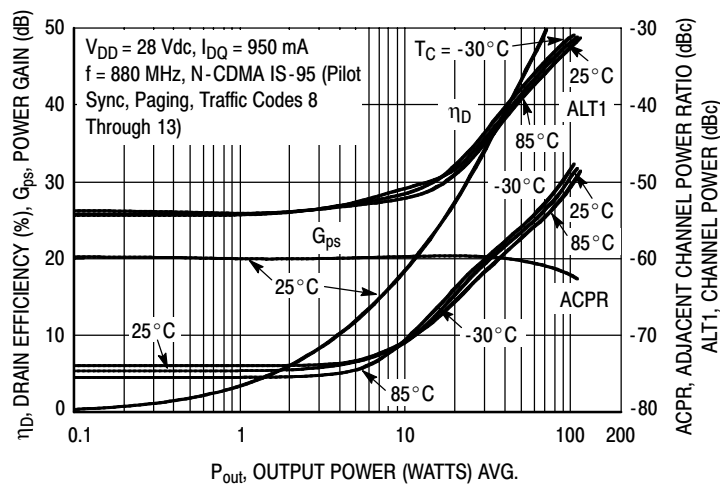
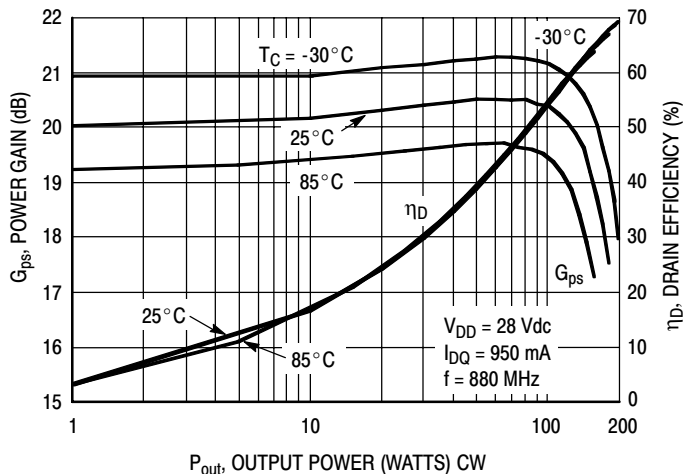
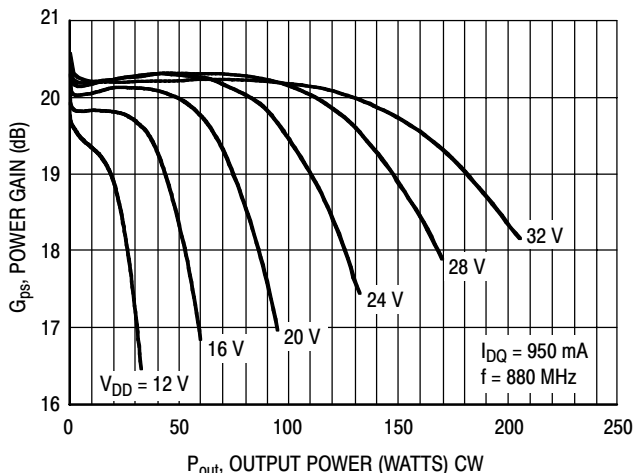


Figure 10. Single-Carrier N-CDMA ACPR, ALT1, Power Gain and Drain Efficiency versus Output Power

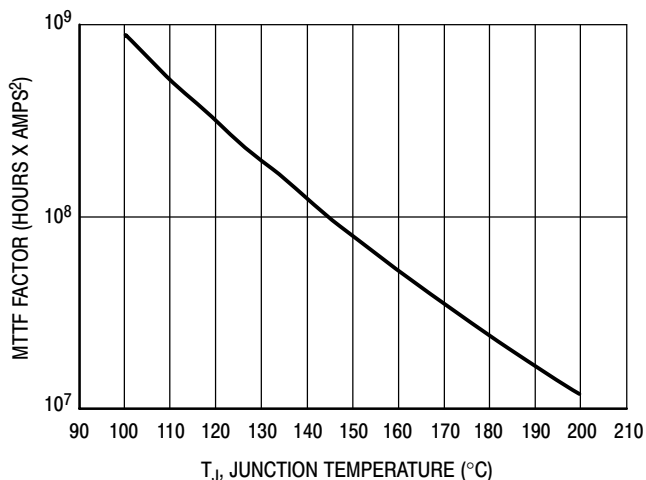
## TYPICAL CHARACTERISTICS



**Figure 11. Power Gain and Drain Efficiency versus CW Output Power**



**Figure 12. Power Gain versus Output Power**

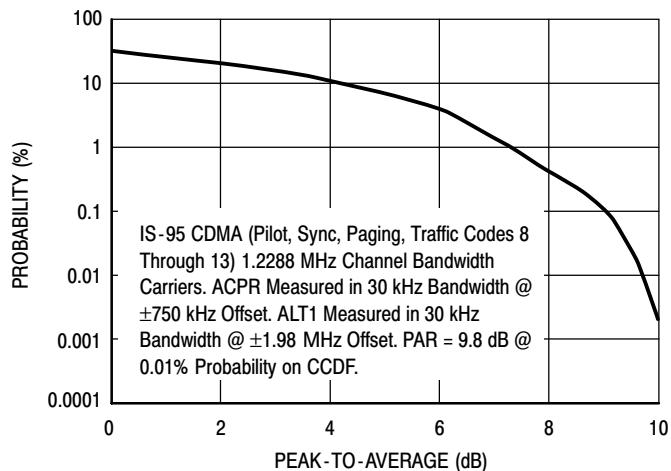


This above graph displays calculated MTTF in hours x ampere<sup>2</sup> drain current. Life tests at elevated temperatures have correlated to better than ±10% of the theoretical prediction for metal failure. Divide MTTF factor by  $I_D^2$  for MTTF in a particular application.

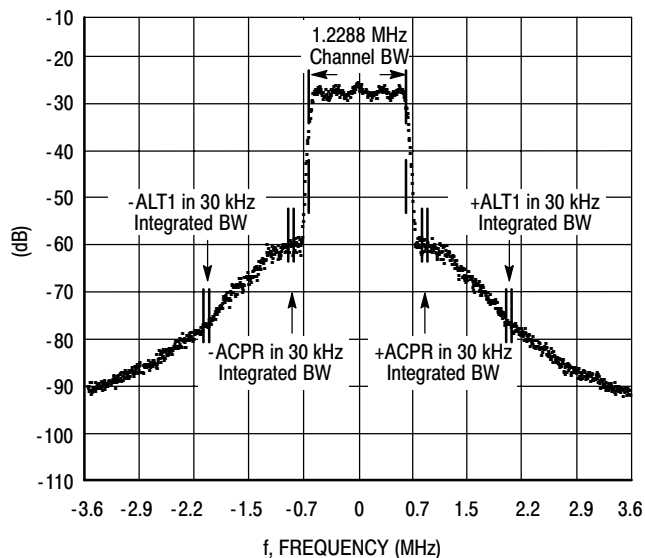
**Figure 13. MTTF Factor versus Junction Temperature**



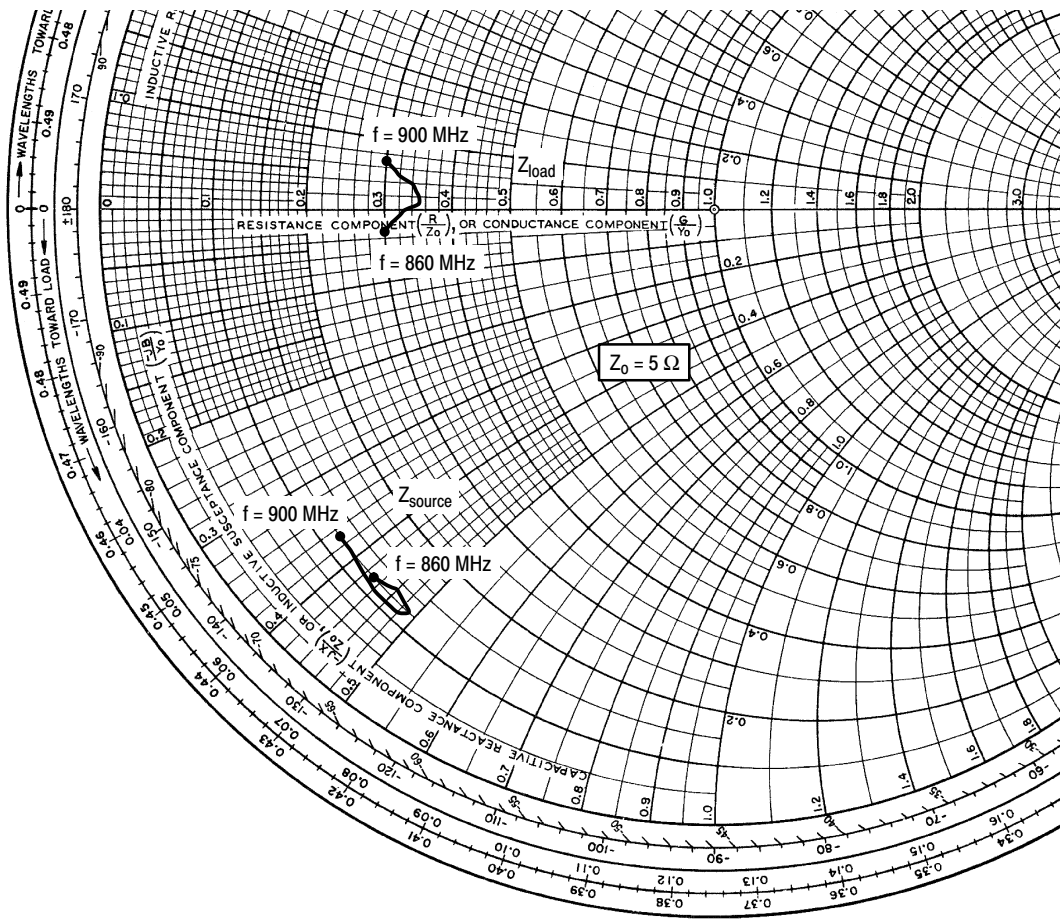
## N-CDMA TEST SIGNAL



**Figure 14. Single-Carrier CCDF N-CDMA**



**Figure 15. Single-Carrier N-CDMA Spectrum**



$V_{DD} = 28 \text{ Vdc}$ ,  $I_{DQ} = 950 \text{ mA}$ ,  $P_{out} = 27 \text{ W Avg.}$

f MHz	$Z_{source}$ $\Omega$	$Z_{load}$ $\Omega$
860	$0.62 - j2.13$	$1.48 - j0.14$
865	$0.64 - j2.31$	$1.56 - j0.09$
870	$0.62 - j2.45$	$1.66 - j0.02$
875	$0.59 - j2.43$	$1.73 + j0.04$
880	$0.57 - j2.42$	$1.74 + j0.11$
885	$0.54 - j2.36$	$1.68 + j0.19$
890	$0.57 - j2.18$	$1.61 + j0.25$
895	$0.58 - j1.94$	$1.52 + j0.33$
900	$0.59 - j1.86$	$1.48 + j0.37$

$Z_{source}$  = Test circuit impedance as measured from gate to ground.

$Z_{load}$  = Test circuit impedance as measured from drain to ground.

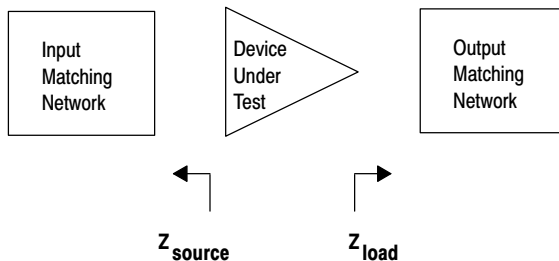
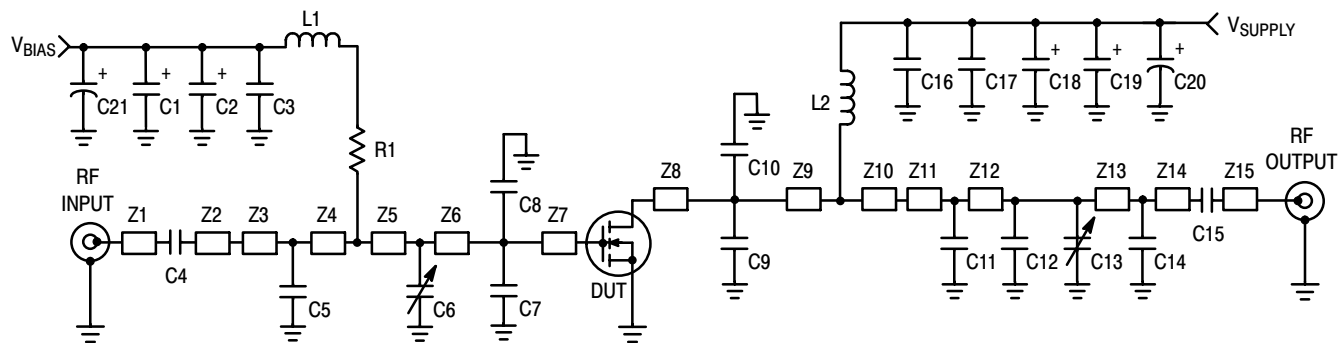


Figure 16. Series Equivalent Source and Load Impedance

## EDGE CHARACTERIZATION



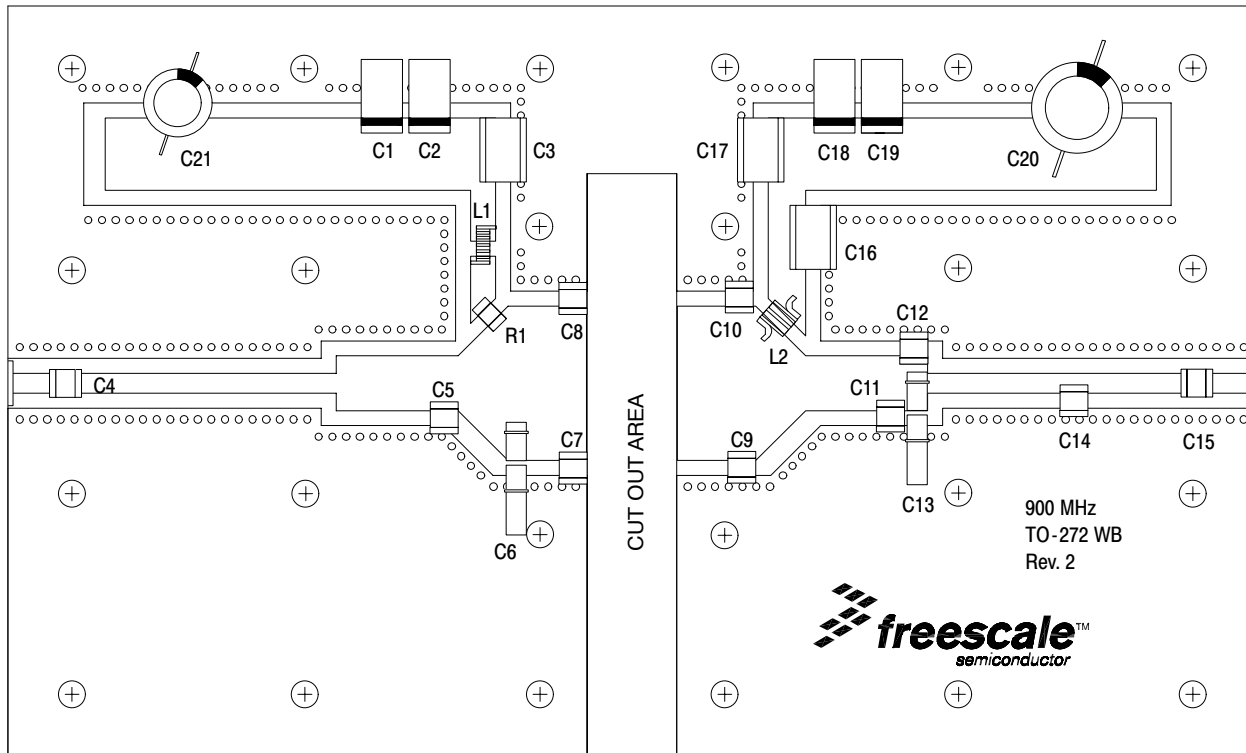
Z1, Z15	0.150" x 0.080" Microstrip	Z9	0.620" x 0.100" x 0.420" Taper
Z2	1.050" x 0.080" Microstrip	Z10	0.420" x 0.100" x 0.220" Taper
Z3	0.330" x 0.220" Microstrip	Z11	0.325" x 0.220" Microstrip
Z4	0.220" x 0.100" x 0.420" Taper	Z12	0.040" x 0.220" Microstrip
Z5	0.420" x 0.100" x 0.620" Taper	Z13	0.475" x 0.080" Microstrip
Z6	0.200" x 0.620" Microstrip	Z14	0.400" x 0.080" Microstrip
Z7, Z8	0.040" x 0.620" Microstrip	PCB	Arlon GX-0300-55-22, 0.030", $\epsilon_r = 2.55$

**Figure 17. MRF6S9125NR1(NBR1) Test Circuit Schematic**

**Table 7. MRF6S9125NR1(NBR1) Test Circuit Component Designations and Values**

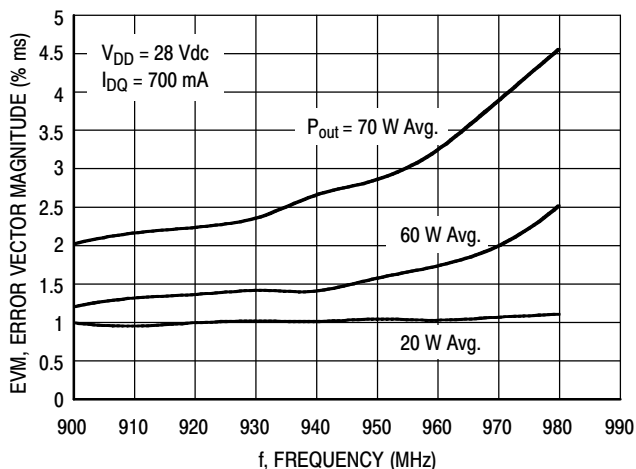
Part	Description	Part Number	Manufacturer
C1, C2	47 $\mu$ F, 16 V Tantalum Capacitors	TPSD476K016R0150	AVX
C3, C16, C17	0.56 $\mu$ F, 50 V Chip Capacitors	C1825C564J5GAC	Kemet
C4	20 pF Chip Capacitor	600B200FT250XT	ATC
C5, C7, C8	6.2 pF Chip Capacitors	600B6R2BT250XT	ATC
C6, C13	0.8-8.0 pF Variable Capacitors, Gigatrim	27291SL	Johanson Dielectrics
C9, C10	11 pF Chip Capacitors	600B110FT250XT	ATC
C11	5.1 pF Chip Capacitor	600B5R1BT250XT	ATC
C12	4.7 pF Chip Capacitor	600B4R7BT250XT	ATC
C14	0.3 pF Chip Capacitor	700B0R3BW500XT	ATC
C15	39 pF Chip Capacitor	700B390FW500XT	ATC
C18, C19	22 $\mu$ F, 35 V Tantalum Capacitors	T491X226K035AS	Kemet
C20	470 $\mu$ F, 63 V Electrolytic Capacitor	NACZF471M63V	Nippon
C21	100 $\mu$ F, 50 V Electrolytic Capacitor	515D107M050BB6A	Multicomp
L1	7.15 nH Inductor	1606-7	Coilcraft
L2	8 nH Inductor	A03T-5	Coilcraft
R1	15 $\Omega$ , 1/4 W Chip Resistor		

## EDGE CHARACTERIZATION

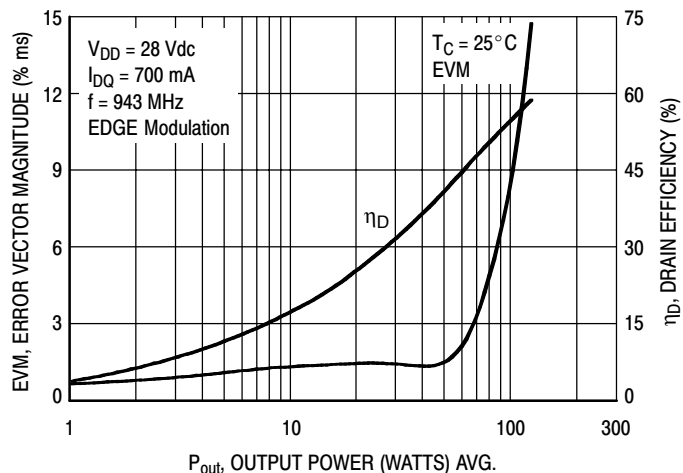


**Figure 18. MRF6S9125NR1(NBR1) Test Circuit Component Layout**

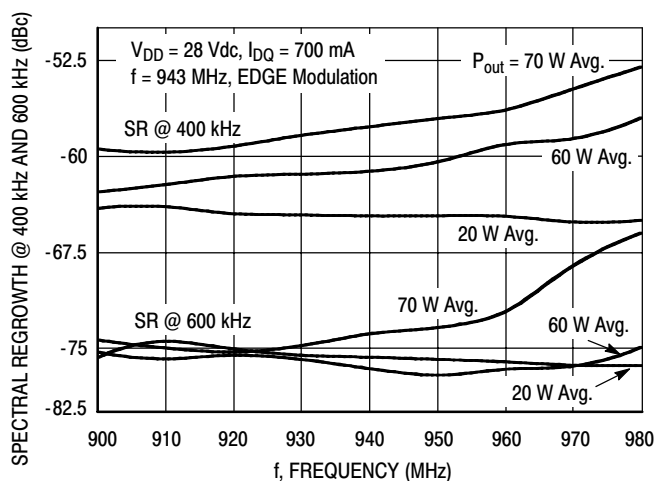
## EDGE CHARACTERIZATION



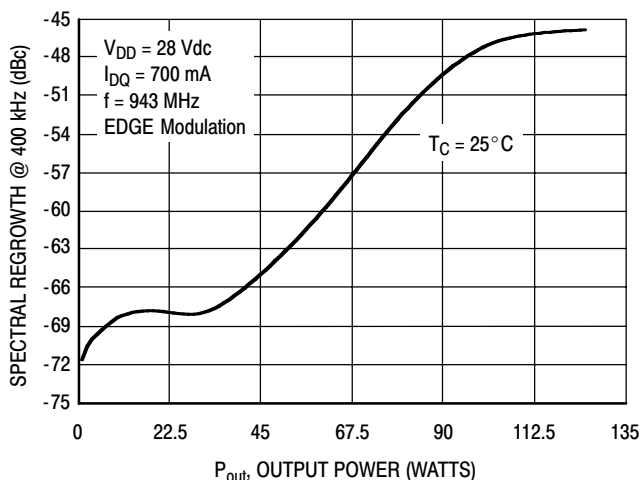
**Figure 19. EVM versus Frequency**



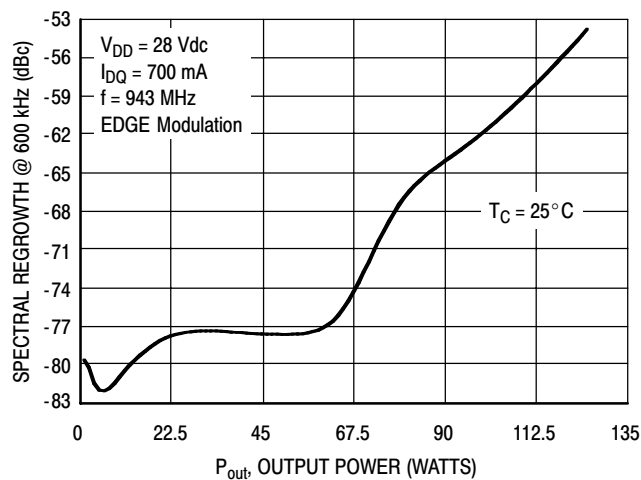
**Figure 20. EVM and Drain Efficiency versus Output Power**



**Figure 21. Spectral Regrowth at 400 kHz and 600 kHz versus Frequency**



**Figure 22. Spectral Regrowth at 400 kHz versus Output Power**



**Figure 23. Spectral Regrowth at 600 kHz versus Output Power**

## EDGE CHARACTERIZATION TEST SIGNAL

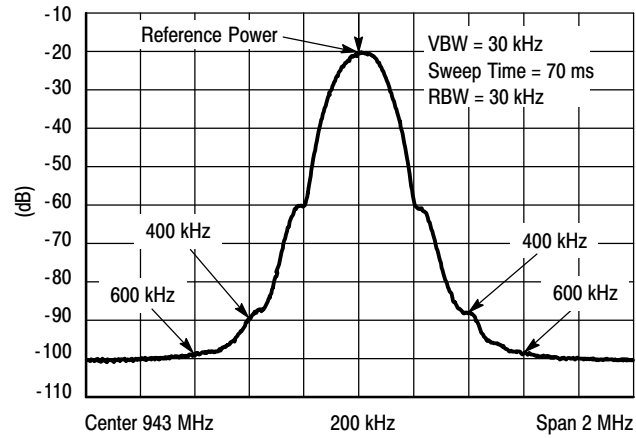
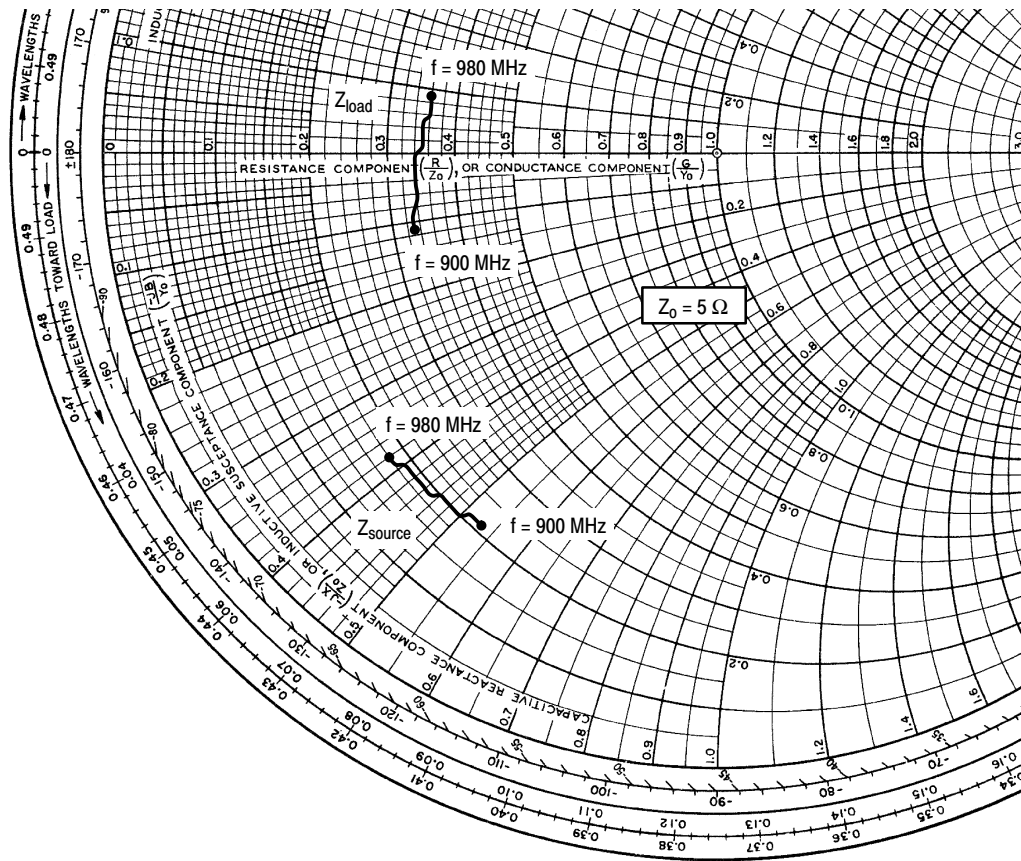


Figure 24. EDGE Spectrum



$V_{DD} = 28 \text{ Vdc}$ ,  $I_{DQ} = 700 \text{ mA}$ ,  $P_{out} = 60 \text{ W Avg.}$

f MHz	$Z_{source}$ $\Omega$	$Z_{load}$ $\Omega$
900	$1.04 - j2.65$	$1.66 - j0.56$
905	$1.04 - j2.60$	$1.66 - j0.50$
910	$1.03 - j2.55$	$1.67 - j0.43$
915	$1.02 - j2.51$	$1.68 - j0.37$
920	$1.01 - j2.46$	$1.68 - j0.31$
925	$1.01 - j2.41$	$1.69 - j0.24$
930	$1.00 - j2.36$	$1.70 - j0.18$
935	$0.98 - j2.32$	$1.70 - j0.12$
940	$0.97 - j2.27$	$1.71 - j0.05$
945	$0.96 - j2.22$	$1.72 - j0.00$
950	$0.95 - j2.17$	$1.73 + j0.07$
955	$0.94 - j2.12$	$1.74 + j0.14$
960	$0.94 - j2.08$	$1.76 + j0.20$
965	$0.93 - j2.03$	$1.77 + j0.26$
970	$0.93 - j1.99$	$1.79 + j0.32$
975	$0.92 - j1.94$	$1.80 + j0.39$
980	$0.92 - j1.90$	$1.82 + j0.45$

$Z_{source}$  = Test circuit impedance as measured from gate to ground.

$Z_{load}$  = Test circuit impedance as measured from drain to ground.

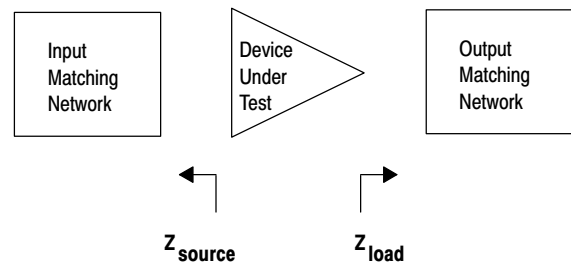
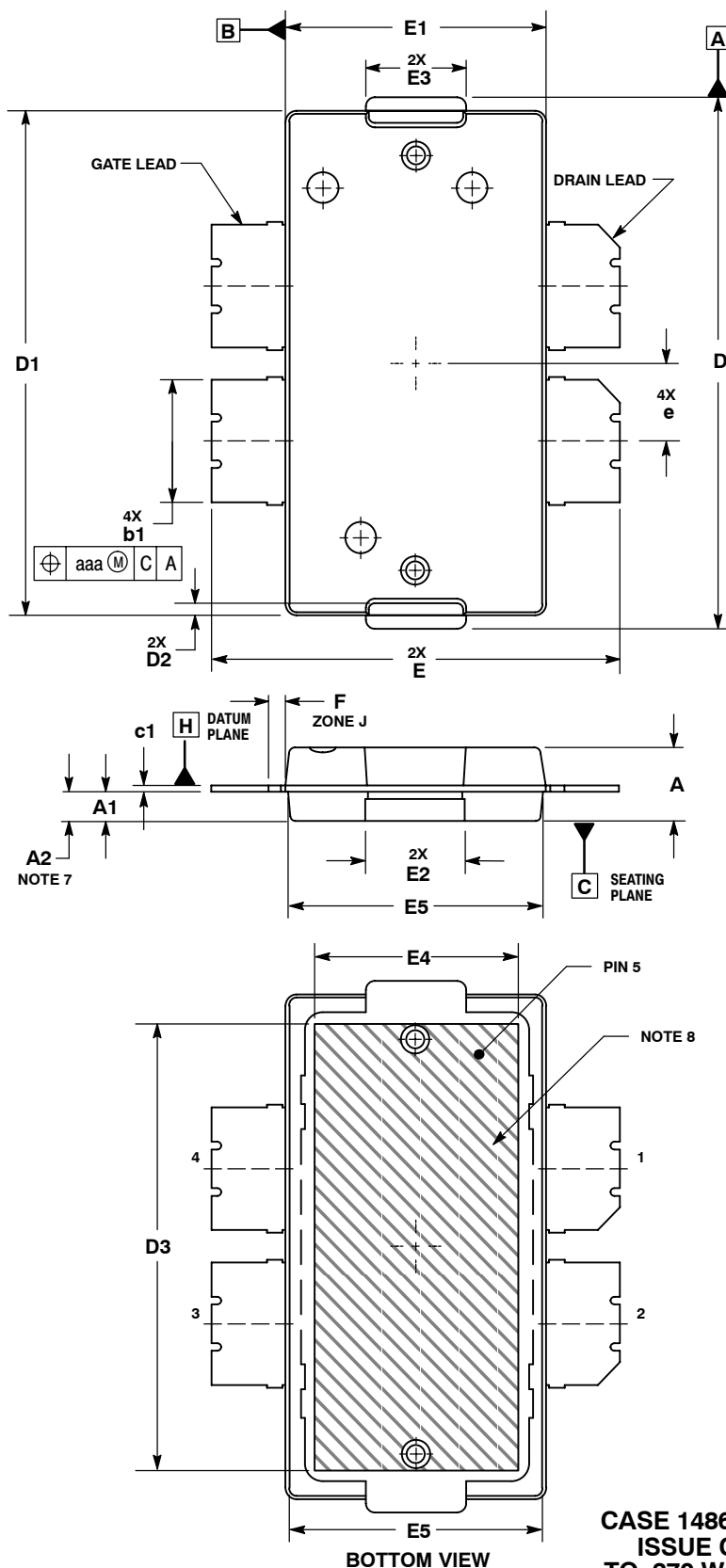


Figure 25. Series Equivalent Source and Load Impedance for EDGE Characterization Tests

# PACKAGE DIMENSIONS



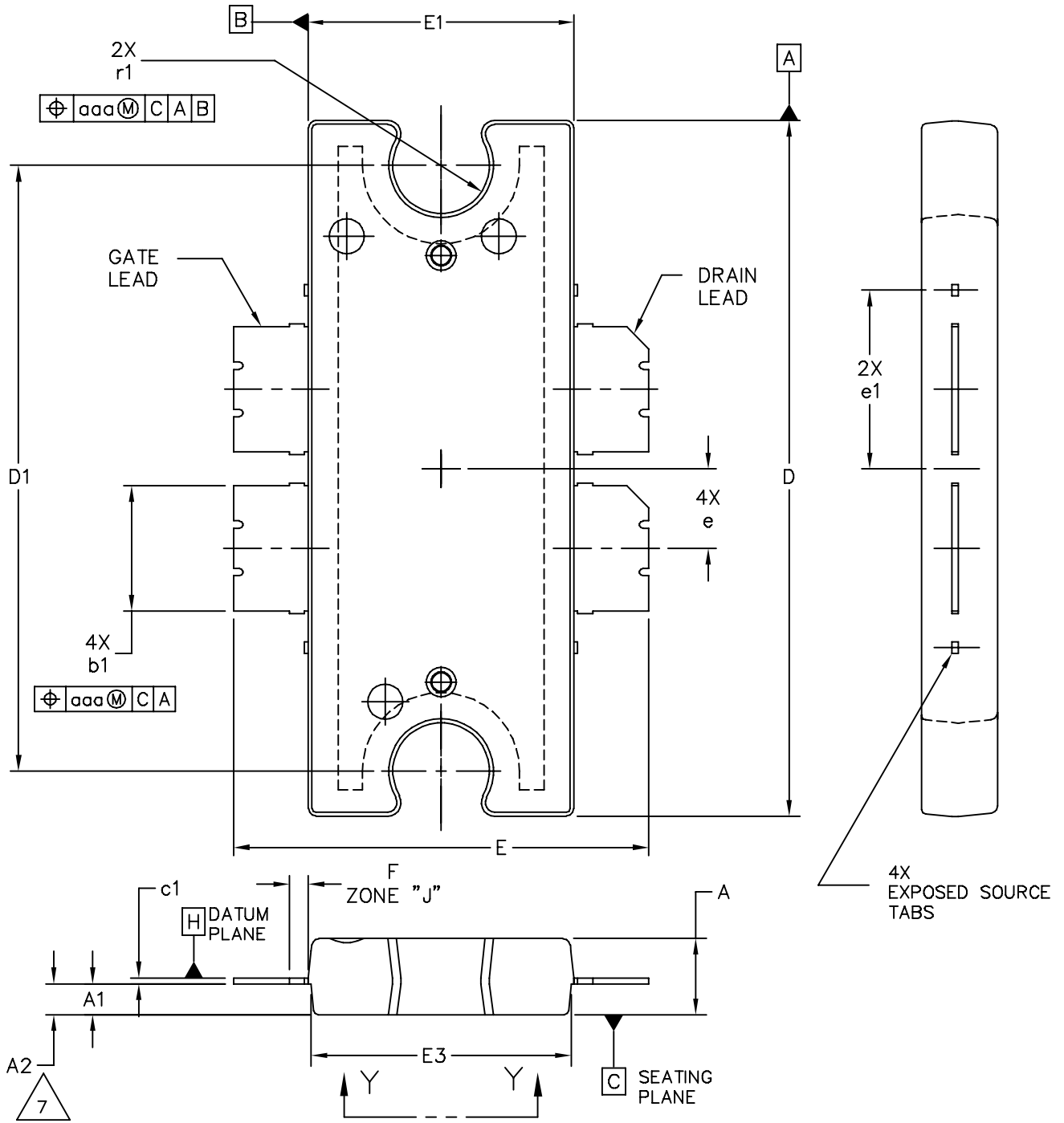
- NOTES:
1. CONTROLLING DIMENSION: INCH.
  2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
  3. DATUM PLANE -H- IS LOCATED AT THE TOP OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE TOP OF THE PARTING LINE.
  4. DIMENSIONS "D" AND "E1" DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS .006 PER SIDE. DIMENSIONS "D" AND "E1" DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.
  5. DIMENSION "b1" DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .005 TOTAL IN EXCESS OF THE "b1" DIMENSION AT MAXIMUM MATERIAL CONDITION.
  6. DATUMS -A- AND -B- TO BE DETERMINED AT DATUM PLANE -H-.
  7. DIMENSION A2 APPLIES WITHIN ZONE "J" ONLY.
  8. HATCHING REPRESENTS THE EXPOSED AREA OF THE HEAT SLUG.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.100	.104	2.54	2.64
A1	.039	.043	0.99	1.09
A2	.040	.042	1.02	1.07
D	.712	.720	18.08	18.29
D1	.688	.692	17.48	17.58
D2	.011	.019	0.28	0.48
D3	.600	---	15.24	---
E	.551	.559	14	14.2
E1	.353	.357	8.97	9.07
E2	.132	.140	3.35	3.56
E3	.124	.132	3.15	3.35
E4	.270	---	6.86	---
E5	.346	.350	8.79	8.89
F	.025 BSC		0.64 BSC	
b1	.164	.170	4.17	4.32
c1	.007	.011	0.18	0.28
e	.106 BSC		2.69 BSC	
aaa	.004		0.10	

- STYLE 1:  
 PIN 1. DRAIN  
 2. DRAIN  
 3. GATE  
 4. GATE  
 5. SOURCE

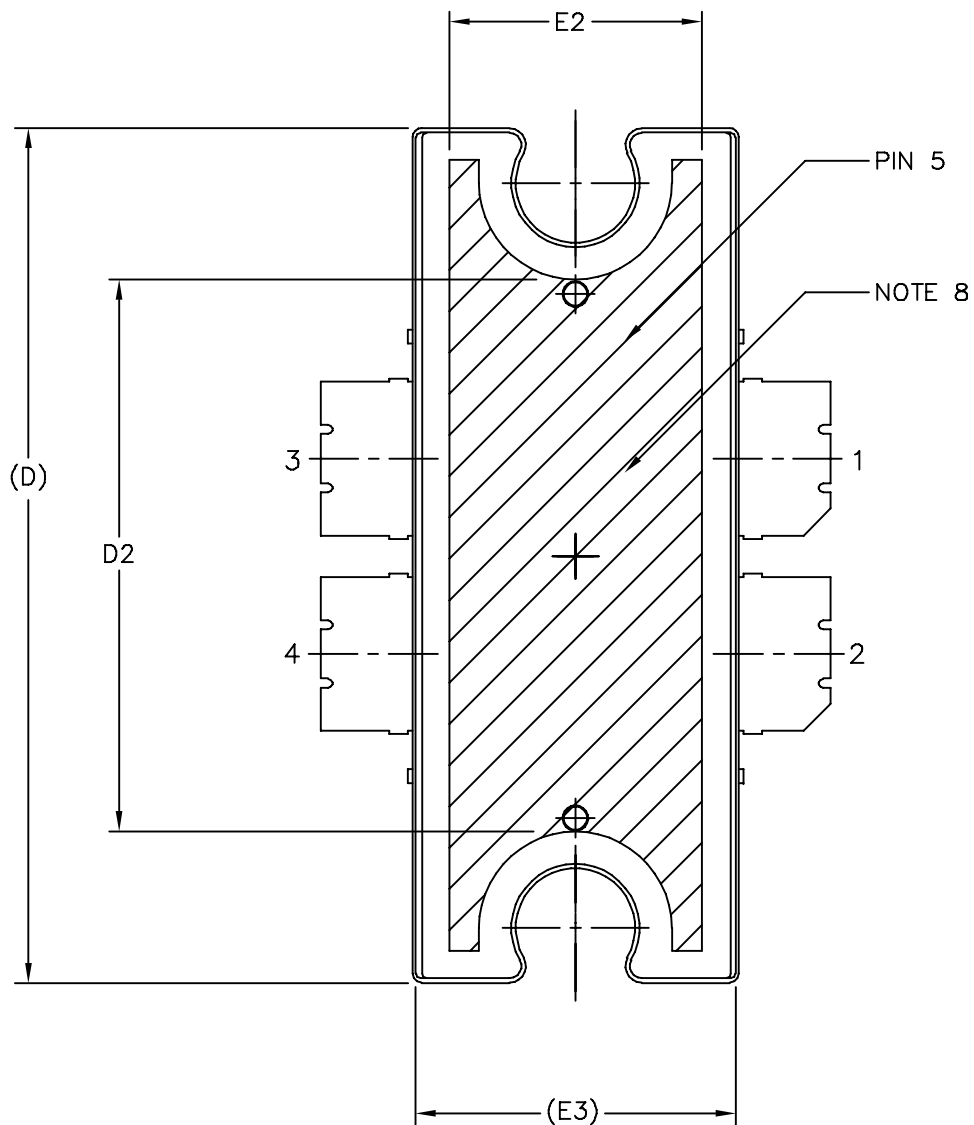
**CASE 1486-03  
 ISSUE C  
 TO-270 WB-4  
 PLASTIC  
 MRF6S9125NR1**





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TITLE:  TO-272 4 LEAD, WIDE BODY			DOCUMENT NO: 98ASA10575D		REV: D
			CASE NUMBER: 1484-04		05 APR 2006
			STANDARD: NON-JEDEC		

MRF6S9125NR1 MRF6S9125NBR1



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TITLE: TO-272 4 LEAD, WIDE BODY	DOCUMENT NO: 98ASA10575D	REV: D	
	CASE NUMBER: 1484-04	05 APR 2006	
	STANDARD: NON-JEDEC		

NOTES:

1. CONTROLLING DIMENSION: INCH
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. DATUM PLANE H IS LOCATED AT THE TOP OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE TOP OF THE PARTING LINE.
4. DIMENSIONS "D" AND "E1" DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS .006 PER SIDE. DIMENSIONS "D" AND "E1" DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.
5. DIMENSIONS "b1" DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .005 TOTAL IN EXCESS OF THE "b1" DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. DATUM A AND B TO BE DETERMINED AT DATUM PLANE H.
7. DIMENSION A2 APPLIES WITHIN ZONE "J" ONLY.
8. HATCHING REPRESENTS EXPOSED AREA OF THE HEAT SLUG. HATCHED AREA SHOWN IS ON THE SAME PLANE.

STYLE 1:

PIN 1 - DRAIN      PIN 2 - DRAIN  
 PIN 3 - GATE      PIN 4 - GATE  
 PIN 5 - SOURCE

DIM	INCH		MILLIMETER		DIM	INCH		MILLIMETER	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	.100	.104	2.54	2.64	b1	.164	.170	4.17	4.32
A1	.039	.043	0.99	1.09	c1	.007	.011	.18	.28
A2	.040	.042	1.02	1.07	r1	.063	.068	1.60	1.73
D	.928	.932	23.57	23.67	e	.106 BSC		2.69 BSC	
D1	.810 BSC		20.57 BSC		e1	.239 INFO ONLY		6.07 INFO ONLY	
D2	.600	---	15.24	---	aaa	.004		.10	
E	.551	.559	14	14.2					
E1	.353	.357	8.97	9.07					
E2	.270	---	6.86	---					
E3	.346	.350	8.79	8.89					
F	.025 BSC		0.64 BSC						

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TITLE:  TO-272 4 LEAD WIDE BODY		DOCUMENT NO: 98ASA10575D		REV: D	
		CASE NUMBER: 1484-04		05 APR 2006	
		STANDARD: NON-JEDEC			

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